

2SC5273

Silicon NPN Triple Diffused

HITACHI

ADE-208-897 (Z)

1st. Edition

Sep. 2000

Application

High voltage amplifier

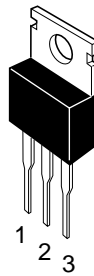
Features

- High brakedown voltage

$$V_{(BR)CEO} = 1300 \text{ V min}$$

Outline

TO-220AB



1. Base
2. Collector
(Flange)
3. Emitter

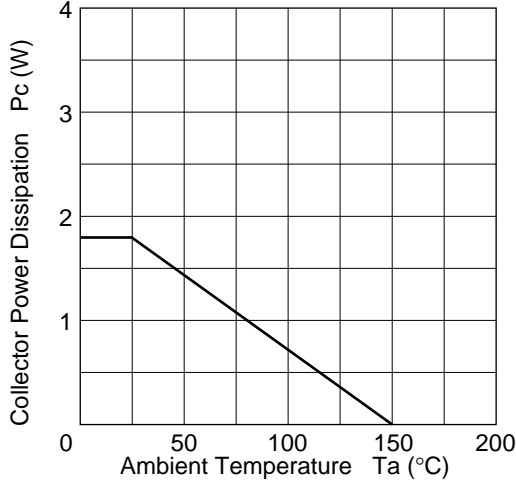
Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	1300	V
Collector to emitter voltage	V_{CEO}	1300	V
Emitter to base voltage	V_{EBO}	6	V
Collector current	I_C	30	mA
Collector peak current	$I_{C(peak)}$	60	mA
Collector power dissipation	P_C	1.8	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

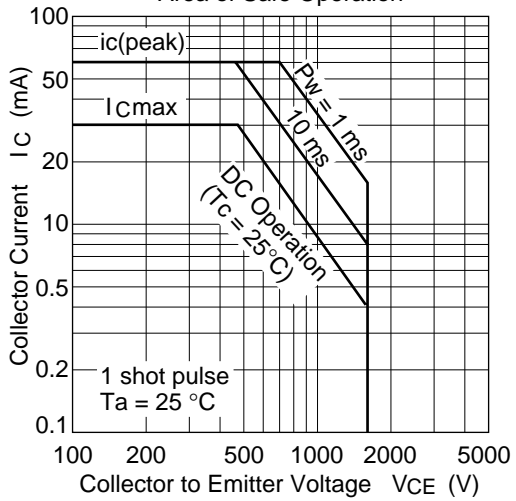
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector cutoff current	I_{CES}	—	—	10	μA	$V_{CE} = 1300\text{ V}, R_{BE} = 0$
Collector cutoff current	I_{CEO}	—	—	100	μA	$V_{CE} = 1300\text{ V}, R_{BE} = \infty$
Emitter cutoff current	I_{EBO}	—	—	10	μA	$V_{EB} = 6\text{ V}, I_C = 0$
DC current transfer ratio	h_{FE}	10	—	—		$V_{CE} = 5\text{ V}, I_C = 1\text{ mA}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	5.0	V	$I_C = 10\text{ mA}, I_B = 2\text{ mA}$
Gain bandwidth product	f_T	—	5.5	—	MHz	$V_{CE} = 20\text{ V}, I_C = 1\text{ mA}$
Collector output capacitance	C_{ob}	—	3.4	—	pF	$V_{CB} = 100\text{ V}, I_E = 0, f = 1\text{ MHz}$

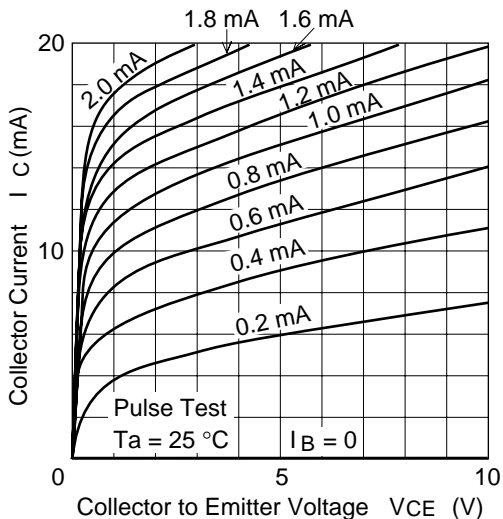
Maximum Collector Power
Dissipation Curve



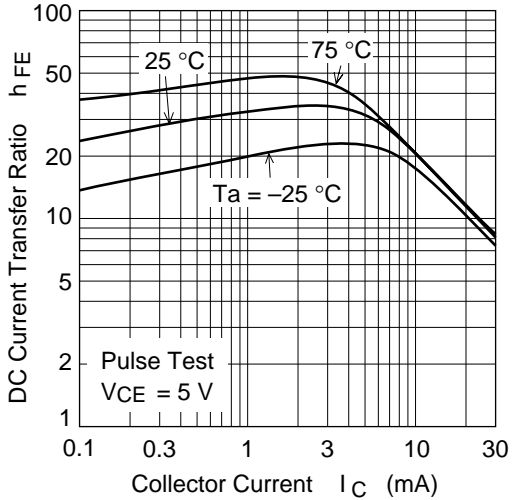
Area of Safe Operation



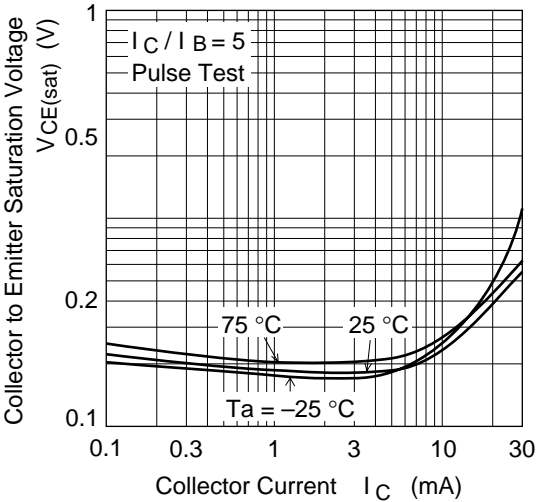
Typical Output Characteristics



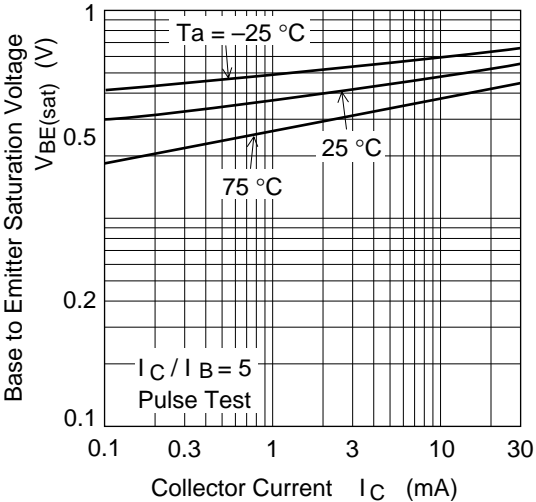
DC Current Transfer Ratio vs.
Collector Current



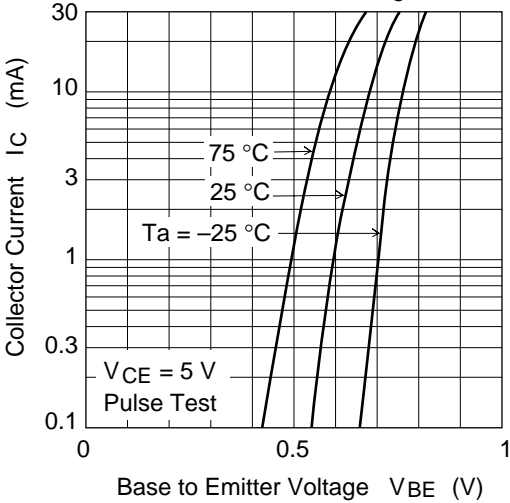
Collector to Emitter Saturation Voltage
vs. Collector Current



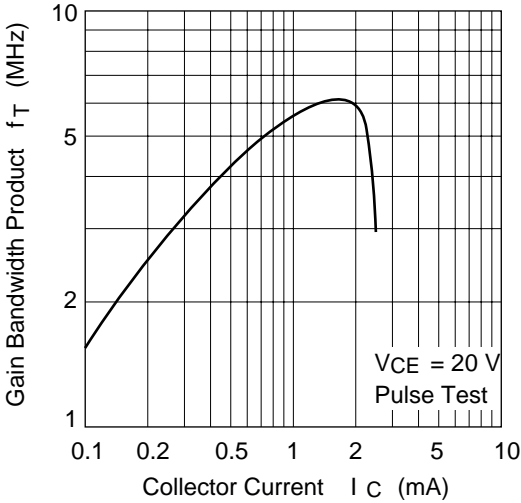
Base to Emitter Saturation Voltage
vs. Collector Current

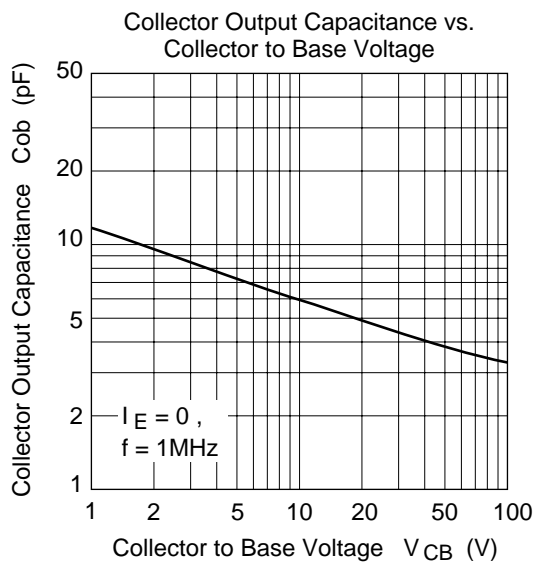


Collector Current vs.
Base to Emitter Voltage



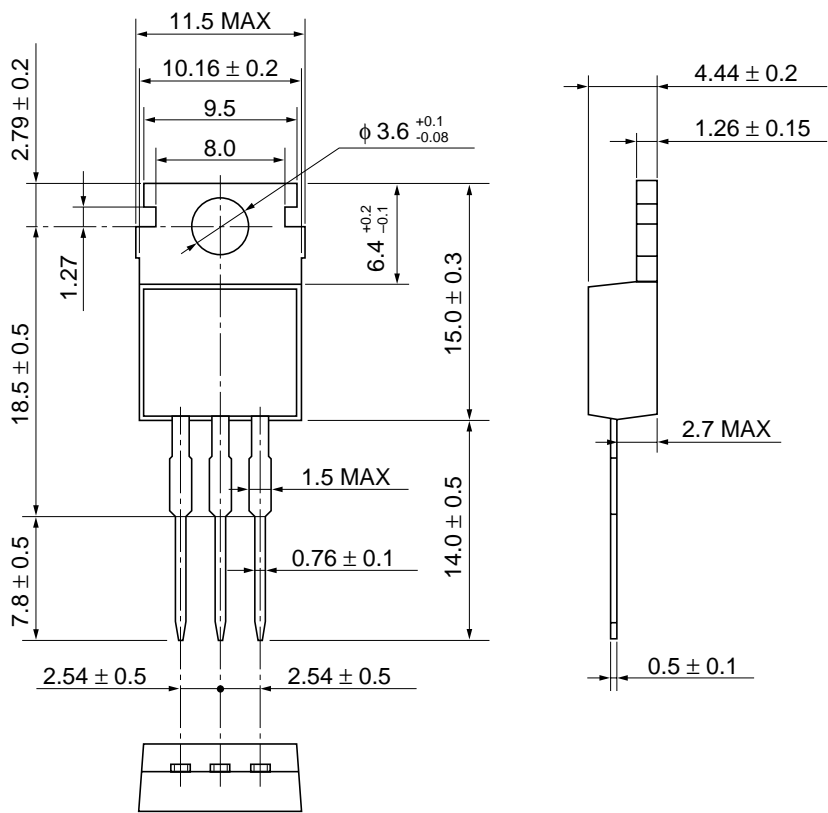
Gain Bandwidth Product vs.
Collector Current





Package Dimensions

Unit: mm



Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.8 g

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